

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chun-Wen Cheng</td> <td>08/27/2013</td> </tr> <tr> <td>Kai-Chih Liang</td> <td>08/27/2013</td> </tr> <tr> <td>Chia-Hua Chu</td> <td>08/27/2013</td> </tr> </tbody> </table>		Name	Execution Date	Chun-Wen Cheng	08/27/2013	Kai-Chih Liang	08/27/2013	Chia-Hua Chu	08/27/2013				
Name	Execution Date												
Chun-Wen Cheng	08/27/2013												
Kai-Chih Liang	08/27/2013												
Chia-Hua Chu	08/27/2013												
RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Co., Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Hsin-Chu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Co., Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Hsin-Chu Science Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
Name:	Taiwan Semiconductor Manufacturing Co., Ltd.												
Street Address:	No. 8, Li-Hsin Rd. 6												
Internal Address:	Hsin-Chu Science Park												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14013080</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14013080								
Property Type	Number												
Application Number:	14013080												
CORRESPONDENCE DATA													
<p>Fax Number: 2165020601 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 212-502-0600 Email: docketing@eschweilerlaw.com Correspondent Name: Eschweiler & Associates, LLC. Address Line 1: 629 Euclid Avenue, Suite 1000 Address Line 2: National City Bank Building Address Line 4: Cleveland, OHIO 44114</p>													
ATTORNEY DOCKET NUMBER:	TSMCP304US												
NAME OF SUBMITTER:	Thomas G. Eschweiler												
Signature:	/Thomas G. Eschweiler/												

PATENT

Date:

08/29/2013

Total Attachments: 5

source=Assignment#page1.tif

source=Assignment#page2.tif

source=Assignment#page3.tif

source=Assignment#page4.tif

source=Assignment#page5.tif

U.S. Patent Appln. No.

Docket No. TSMCP304US

Filing Date

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Chun-Wen Cheng
No. 15, Alley 11, Lane 100, Jiafeng 1st St.
Hsinchu County
Zhubei City 302
Taiwan (R.O.C.)

Assignor(s):

Kai-Chih Liang
8F, No. 29-1, Zhuangjing 5th St.
Hsinchu County
Zhubei City 302
Taiwan (R.O.C.)

Assignor(s):

Chia-Hua Chu
No. 1, Lane 176, Aikou 6th St.
Hsinchu County
Zhubei City 302
Taiwan (R.O.C.)

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

**"A CMOS-MEMS INTEGRATED FLOW FOR MAKING A PRESSURE
SENSITIVE TRANSDUCER"** for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration and Power of
Attorney); or

U.S. Patent Appln. No.

Docket No. TSMCP304US

Filing Date

☐ was filed on _____ and accorded U.S. Serial No. _____; or☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all

U.S. Patent Appln. No.

Docket No. TSMCP304US

Filing Date

letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

✓ 2013.08.27
Date

✓ Chun-Wen Cheng
Name 1st Inventor Chun-Wen Cheng

U.S. Patent Appln. No.
Filing Date

TSMC Docket No. TSMC2013-0473

Docket No. TSMCP304US

✓ 8/27 '2013
Date

✓ Kai-Chih Liang
Name 2nd Inventor Kai-Chih Liang

U.S. Patent Appln. No.
Filing Date

TSMC Docket No. TSMC2013-0473

Docket No. TSMCP304US

✓ 8/29/2013
Date

✓ Chia-Hua Chu
Name 3rd Inventor Chia-Hua Chu